

# Three-Dimensional Structural and Compositional Analysis of MTJ by STEM/EDX Tomography

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# Agenda

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## 1. Introduction

- MTJ (Multi Tunnel Junction)
- Morphological approach to characterization  
(2D)TEM, 3D-TEM(HAADF-STEM, EDX)

## 2. Experimental

- MRAM structure
- Sample preparation for 3D
- HAADF STEM Tomography
- EDX Tomography

## 3. Results and Discussion

## 4. Conclusion

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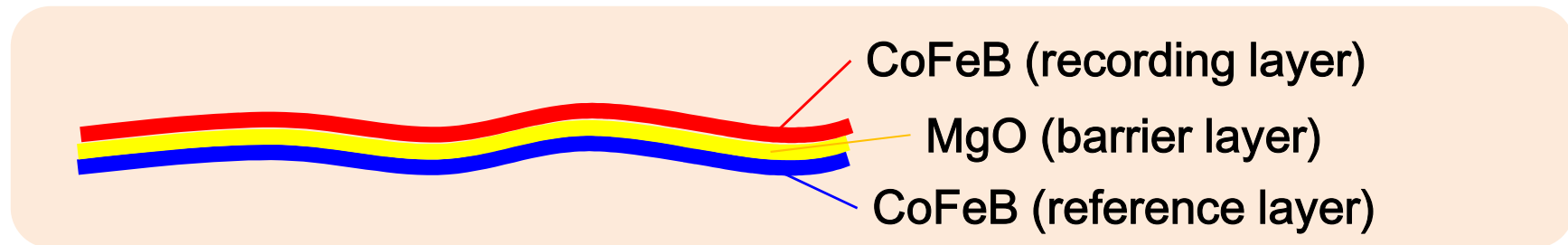
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# Introduction

## MTJ (Multi Tunnel Junction) structure



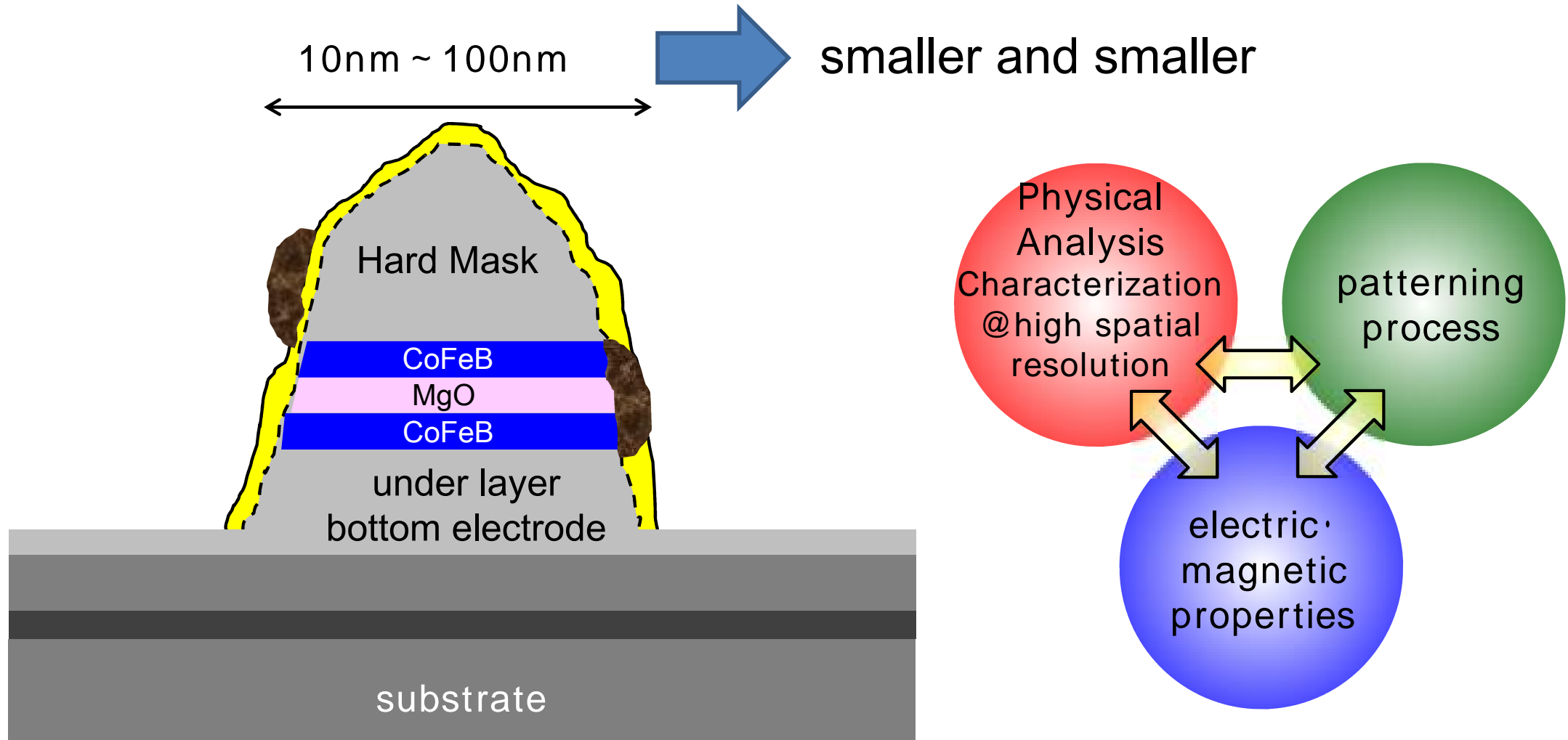
**High speed and Low power consumption**

**MRAM (Magnetic Random Access Memory) is greatly expected to be replaced to conventional volatile cache memory.**

To minimize the size of MRAM, there are several problems such as downscaling, etching damage by the patterning process.

**Characterization of interface roughness etc.  
are very important.**

# MRAM structure and subjects



**TEM is the key tool for MTJ devices**

# Attention points of MRAM characterization by TEM/STEM, EDX, EELS

## Subjects

total device size  
device shape  
roughness of each layer  
composition and diffusion status

side-wall damage

deposits

Hard mask

CoFeB

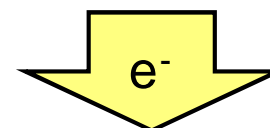
MgO

CoFeB

under layer  
bottom electrode

etching status

substrate



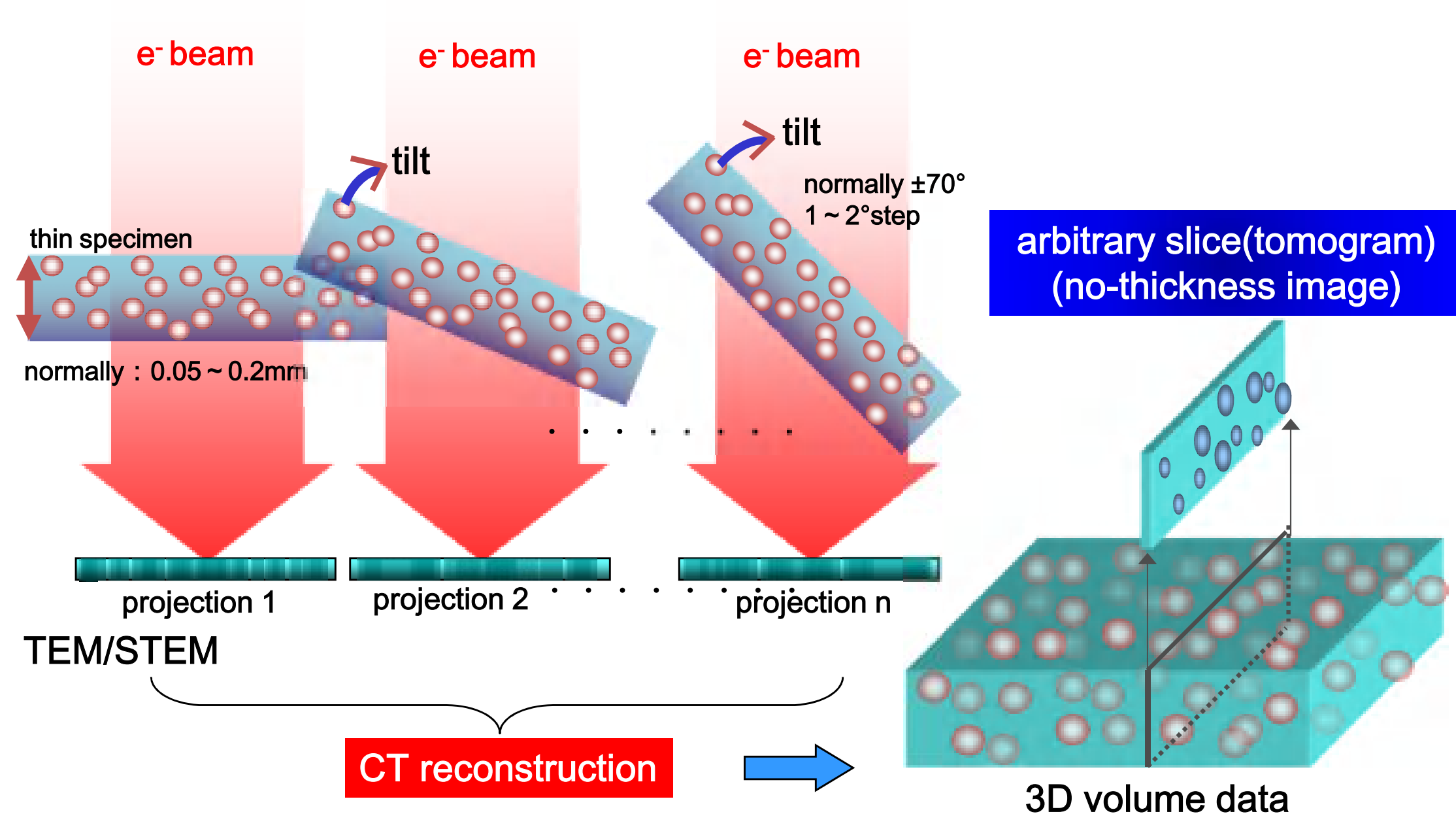
TEM  
specimen

2D-TEM approach is imperfect  
Because information might be overlapped

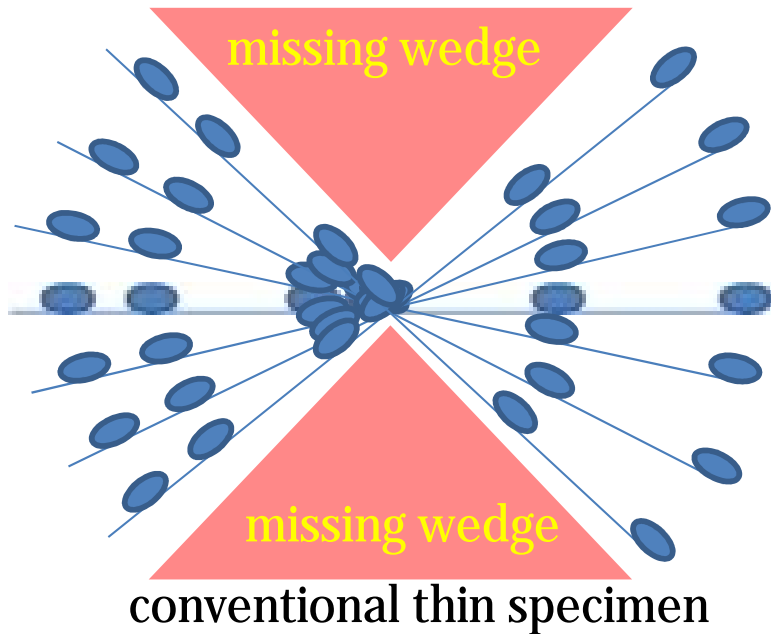


**3D approaches will be needed!**

# Schematic diagram of TEM tomography

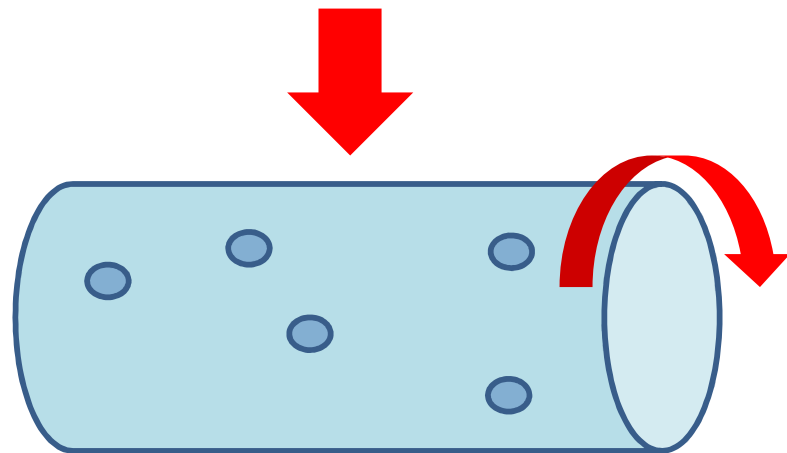


# To overcome TEMT resolution problem



Normal thin specimen  
limits the tilting angle to  $\pm 70^\circ$ ..

“Missing wedge” zone degrades resolution.



Rod-shape specimen  
allows tilting angle to  $\pm 90^\circ$ ..

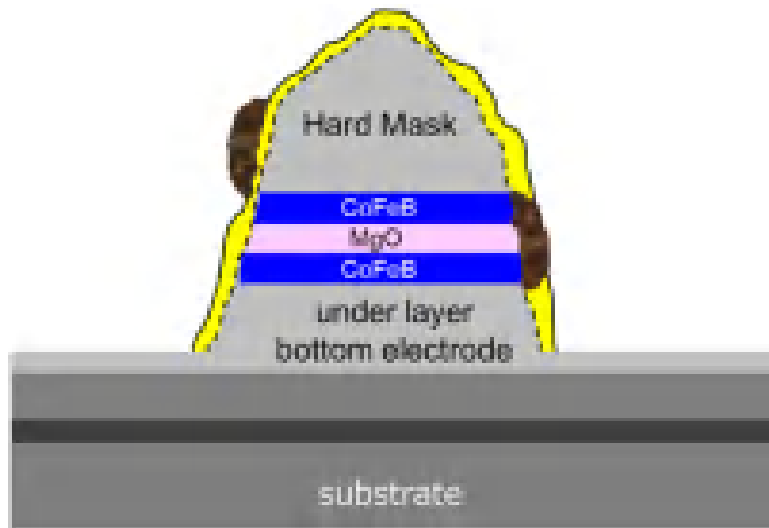
No “Missing wedge”

(Kawase et al., Ultramicroscopy. 2007 Jan;107(1):8-15.)

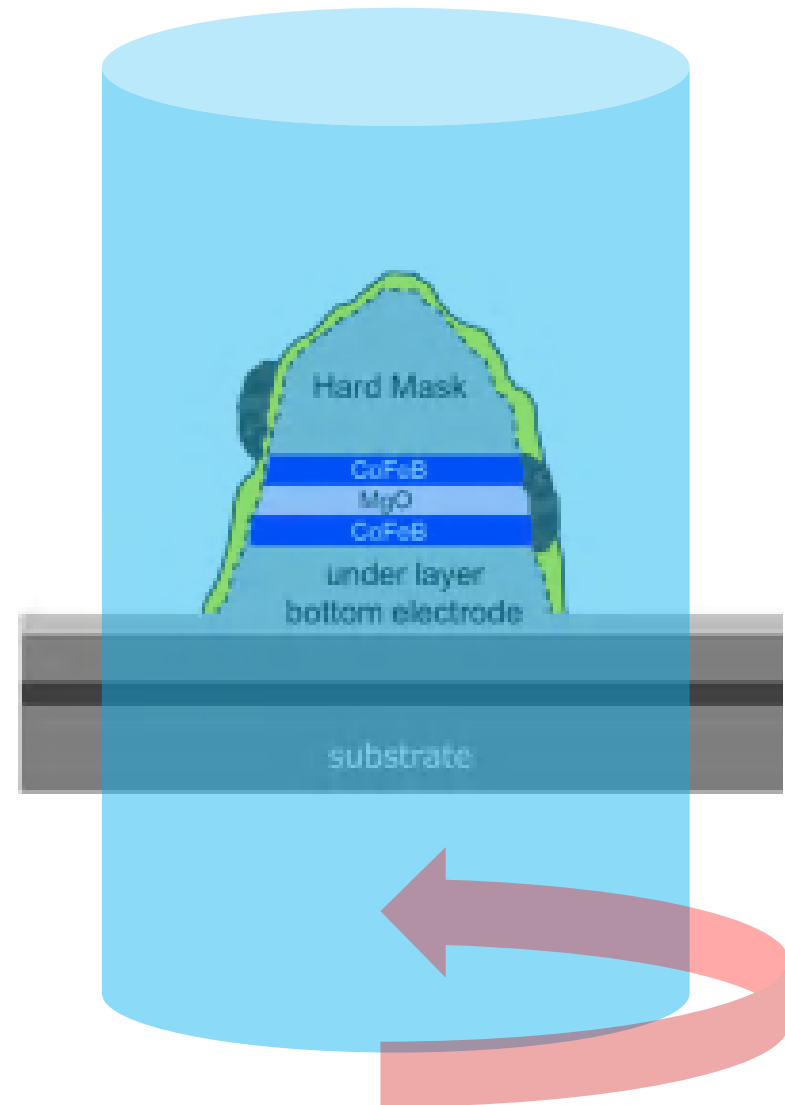
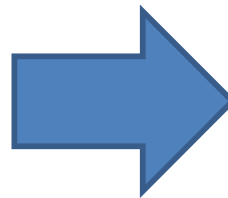


# TEMT approaches for MRAM

Think about MRAM device structure...



It is originally **small conical** structure.



**We aim to get whole information of MRAM by rod-shape TEMT**

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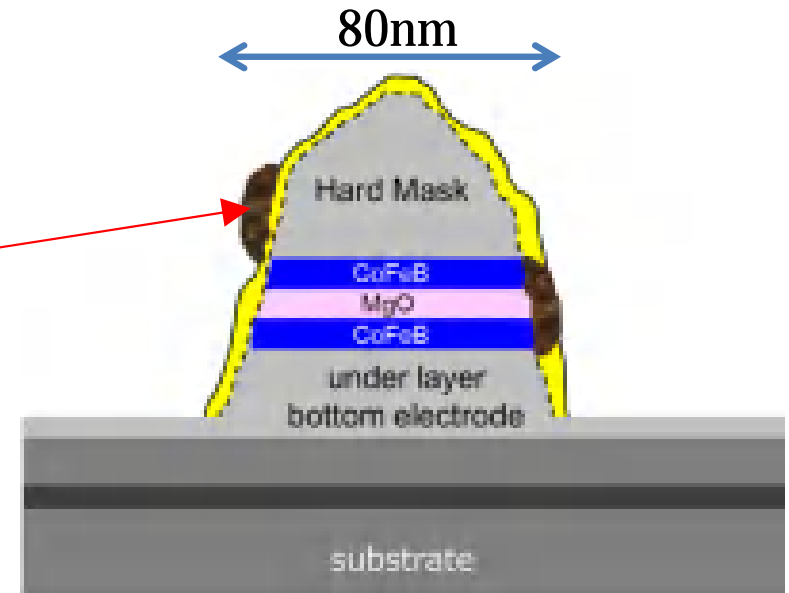
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# Sample and experimental

Sample : 80nm MTJ (MRAM) device model  
double junction structure  
prepared by Tohoku univ. (CIES)

**Deposits were remained by intent  
for feasibility study .**



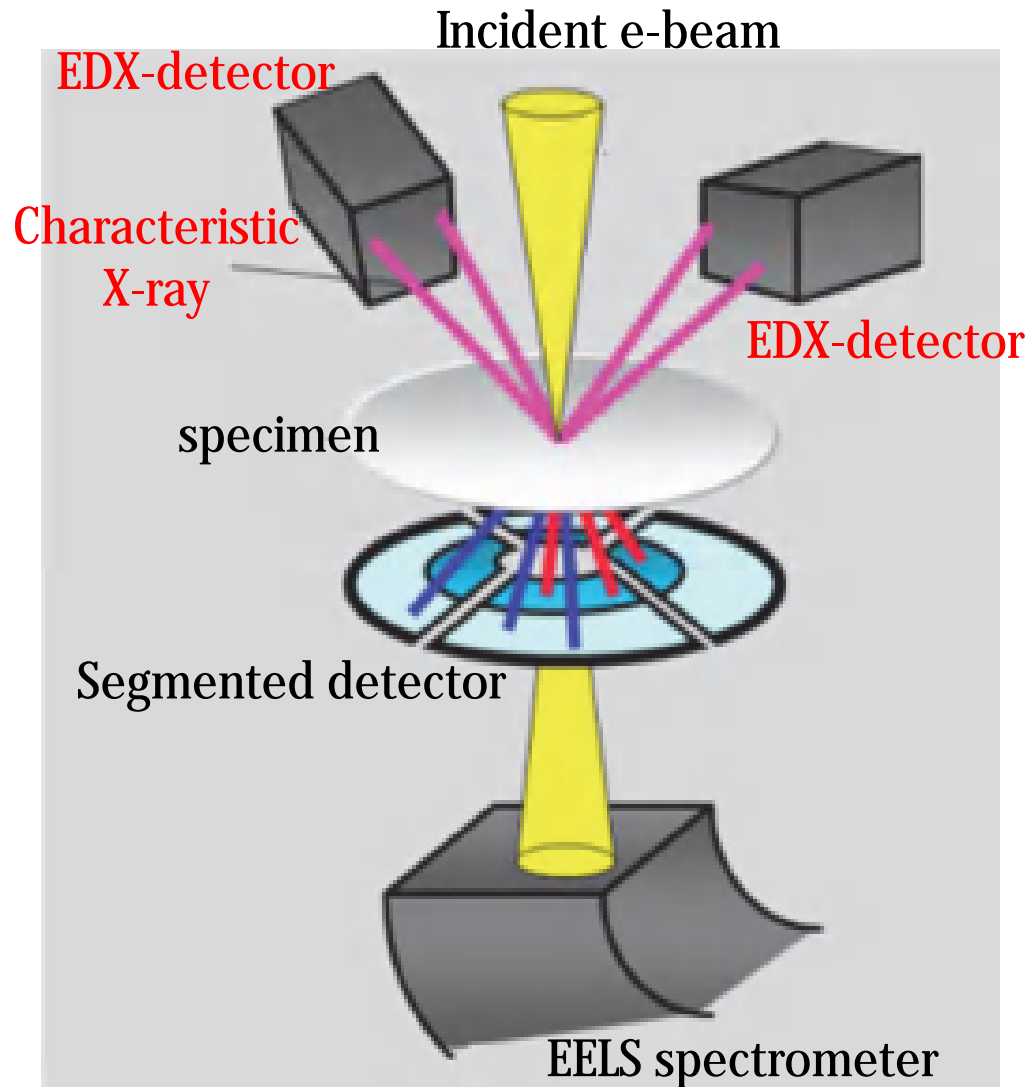
apparatus :

FIB: Thermo-Fischer Helios 660 (SEM/FIB dual beam)

STEM: JEOL JEM-ARM200F Dual-X (Cs-corrected STEM/double EDX detector)

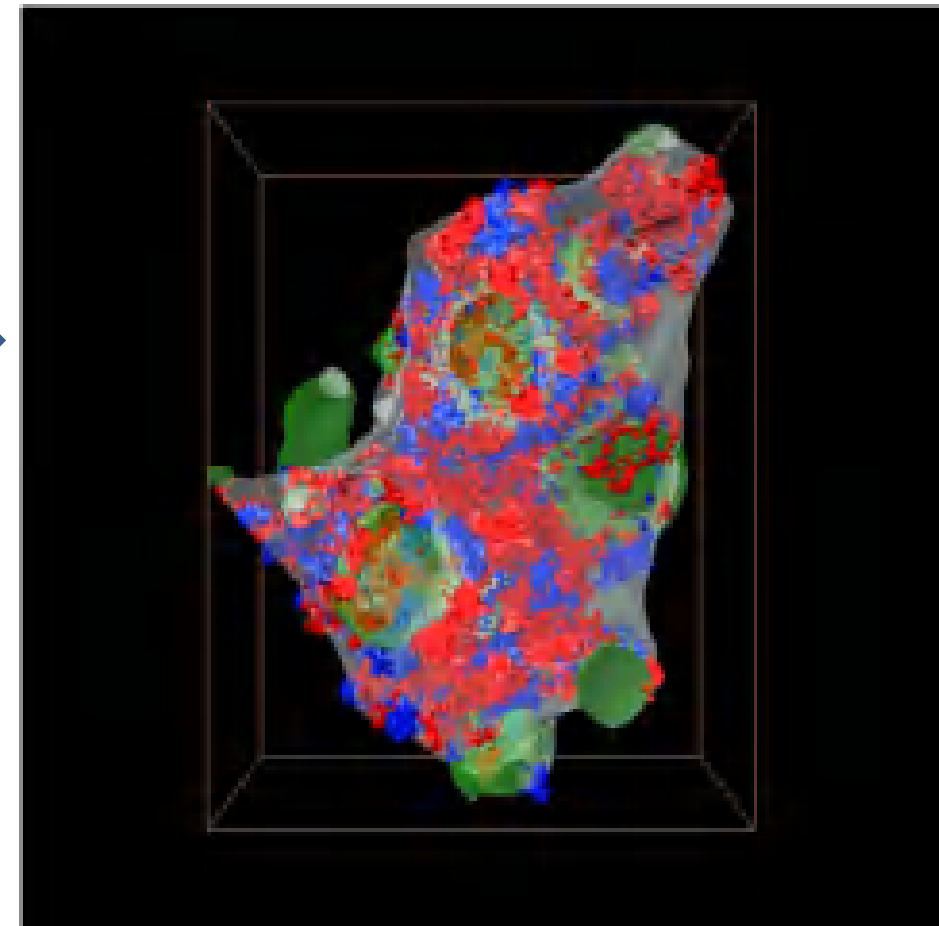
software : TEMography (SiF)

# EDX tomography



Example : sunscreen creme @-170°C

O-Si-Ti-Zn



20nm

Inamoto, 2017

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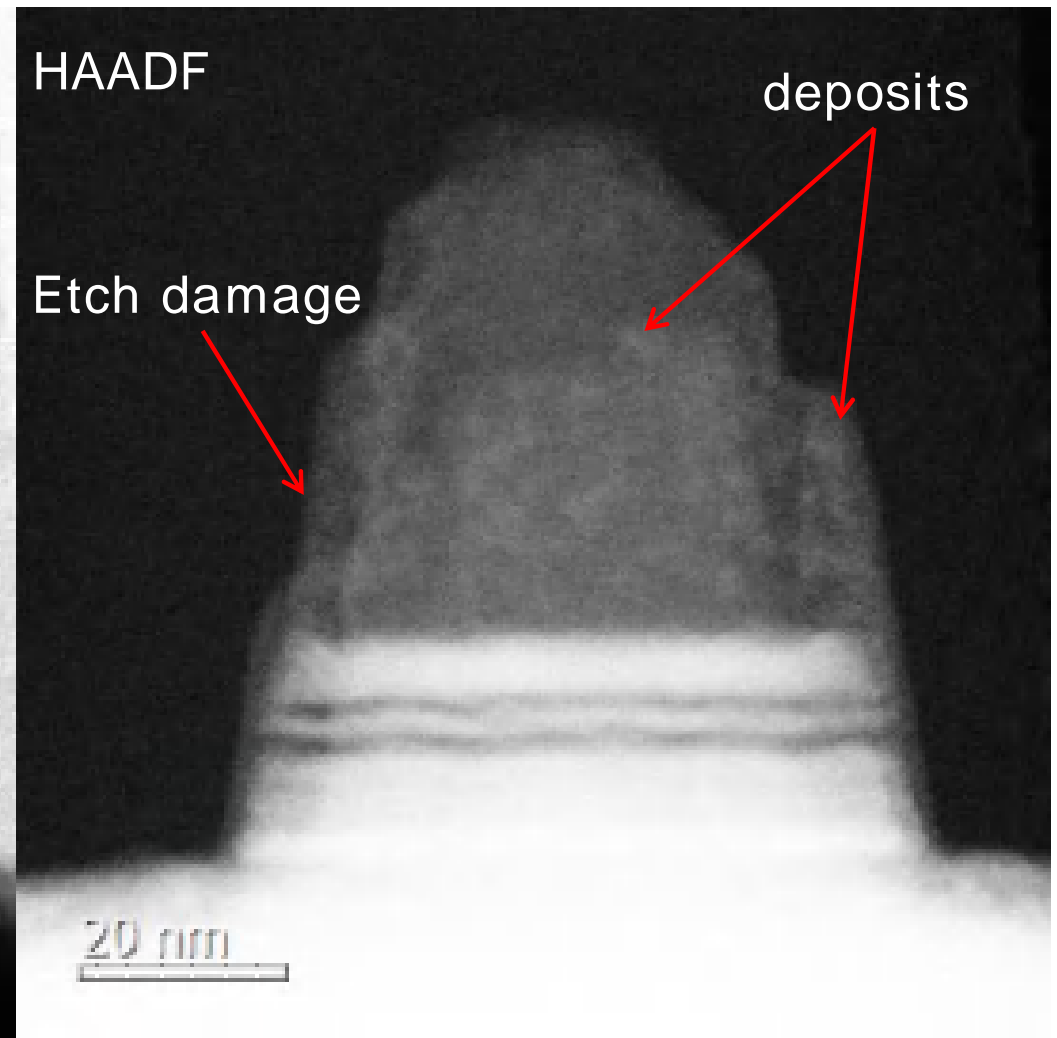
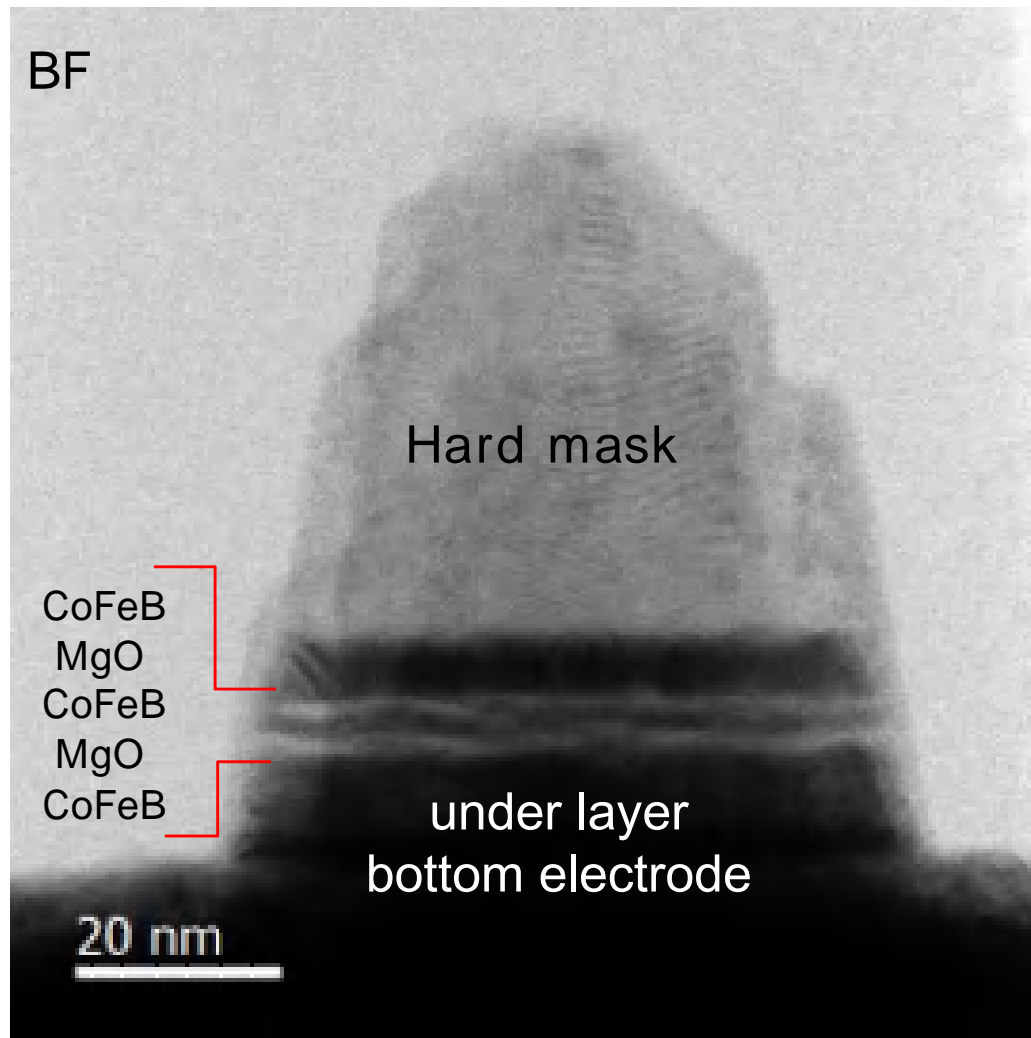
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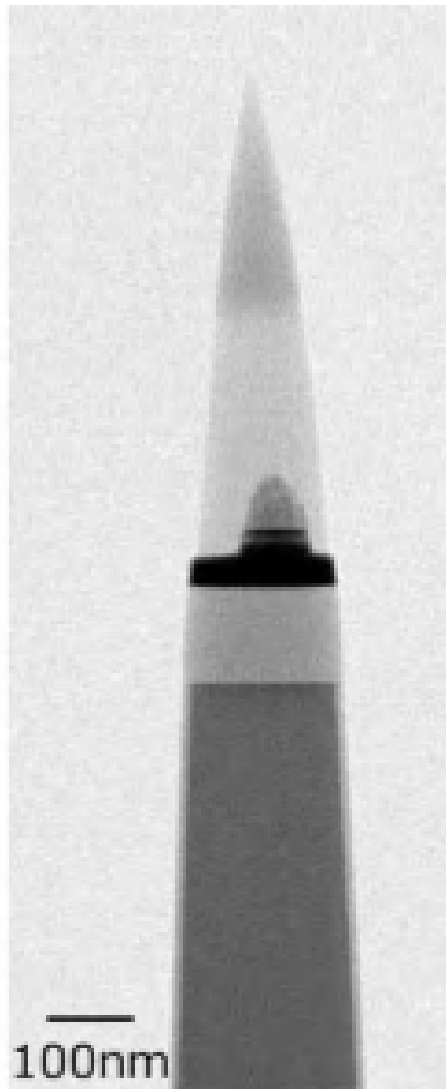
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# 2D STEM observation

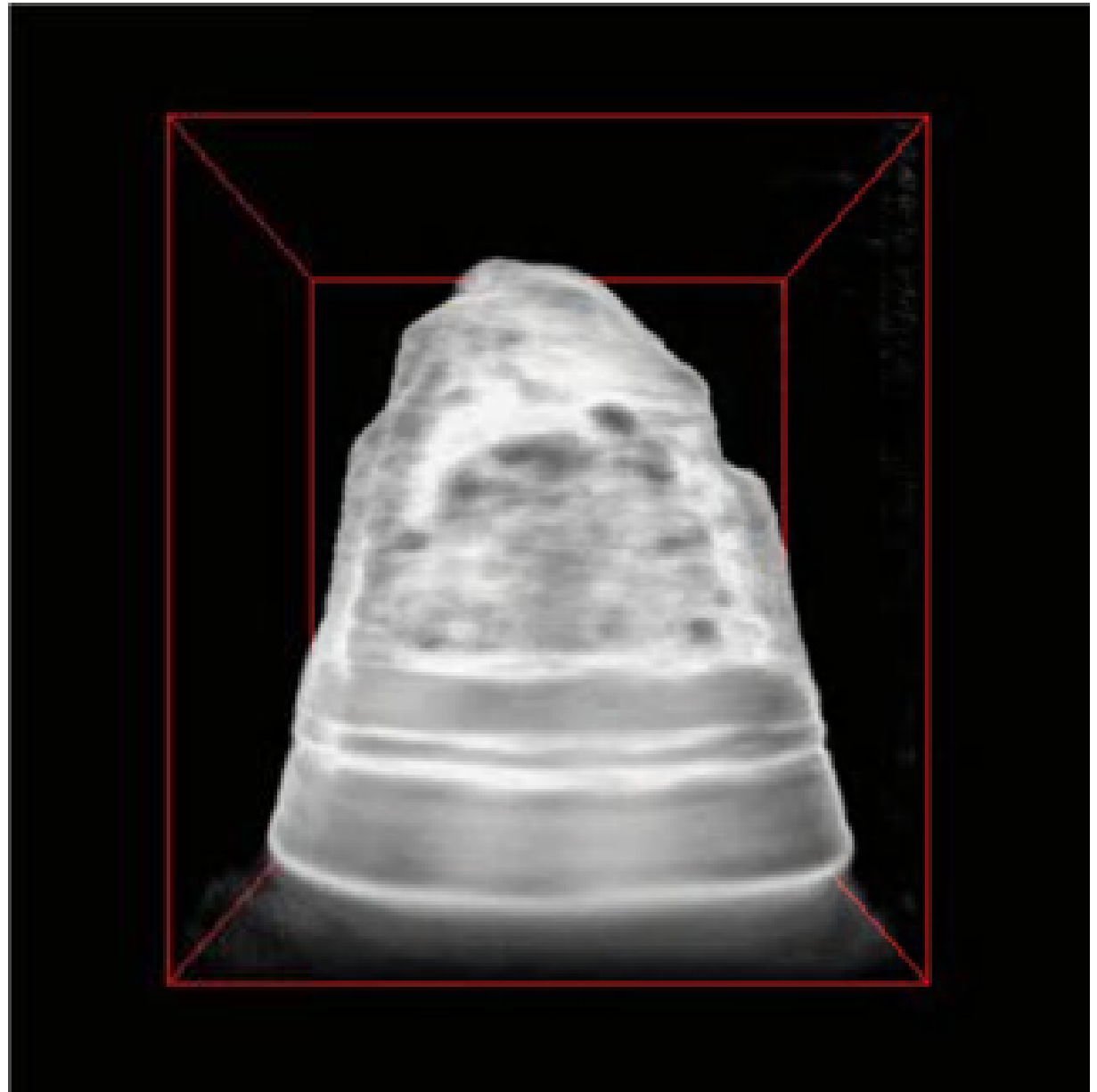


MTJ(double junction) structure and deposits have been observed,  
but 2D projection is not so clear. 3D

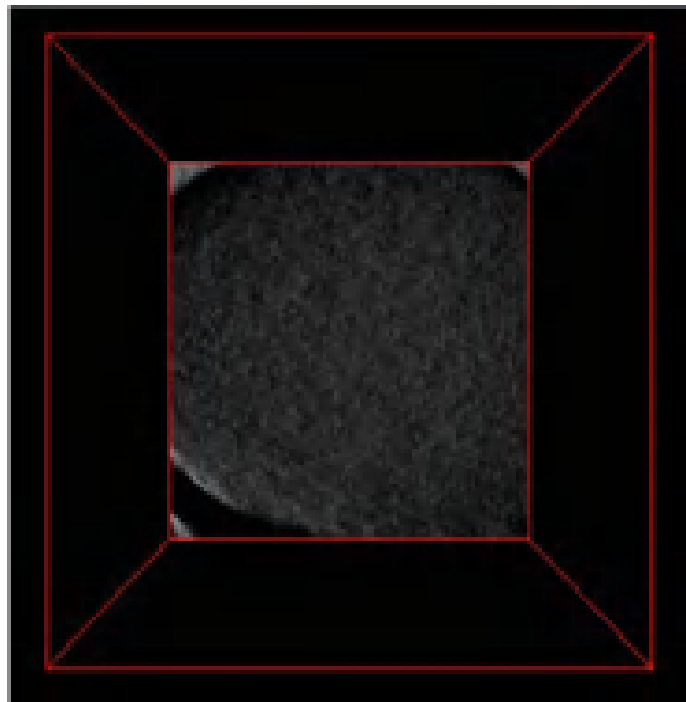
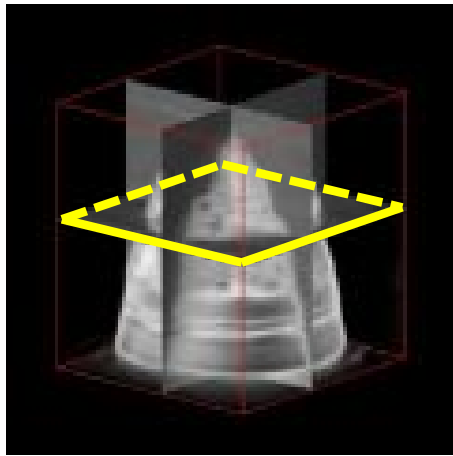
# HAADF 3D STEM



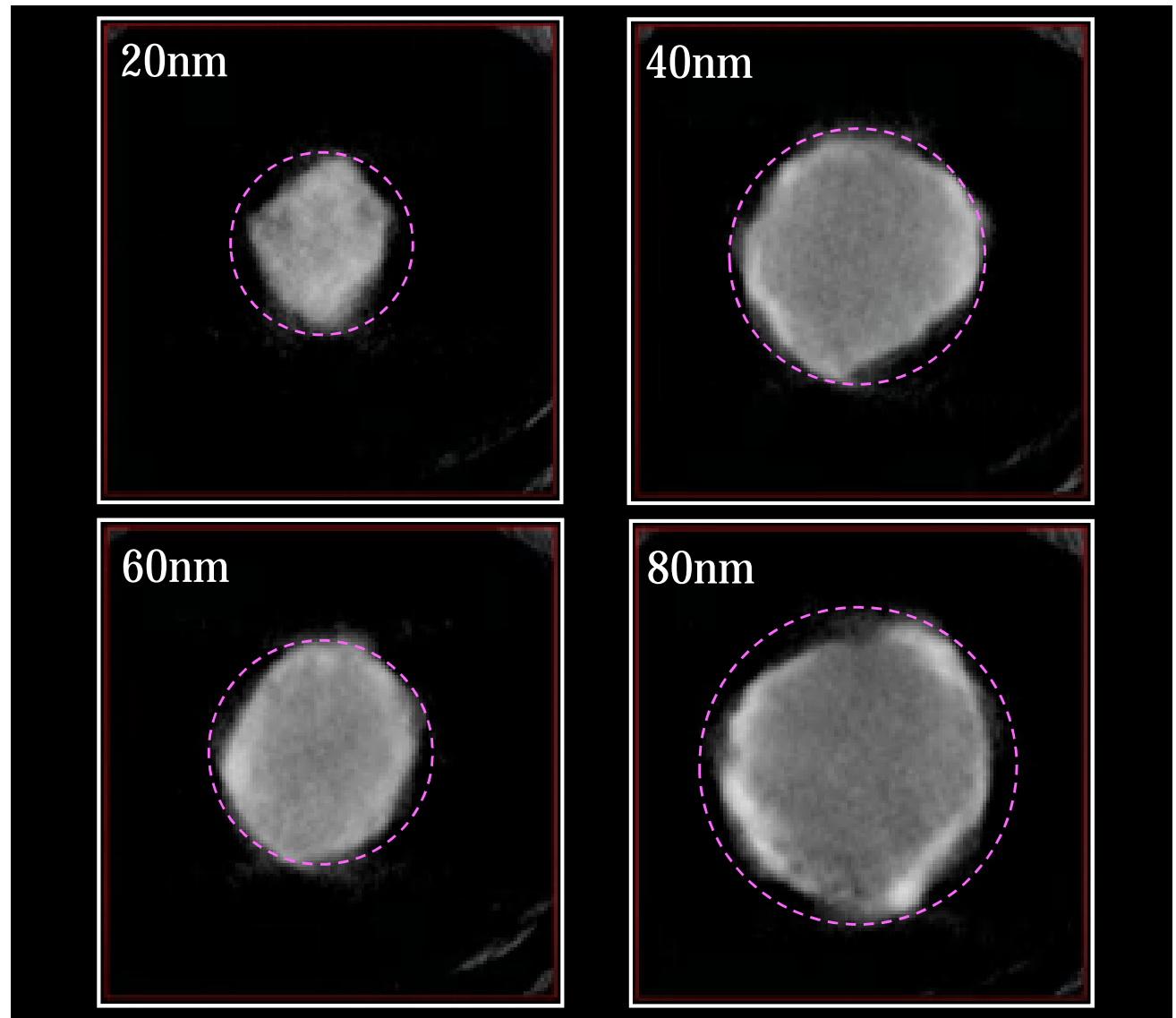
Rod-shape specimen by FIB



# Tomogram series : from Top to Bottom



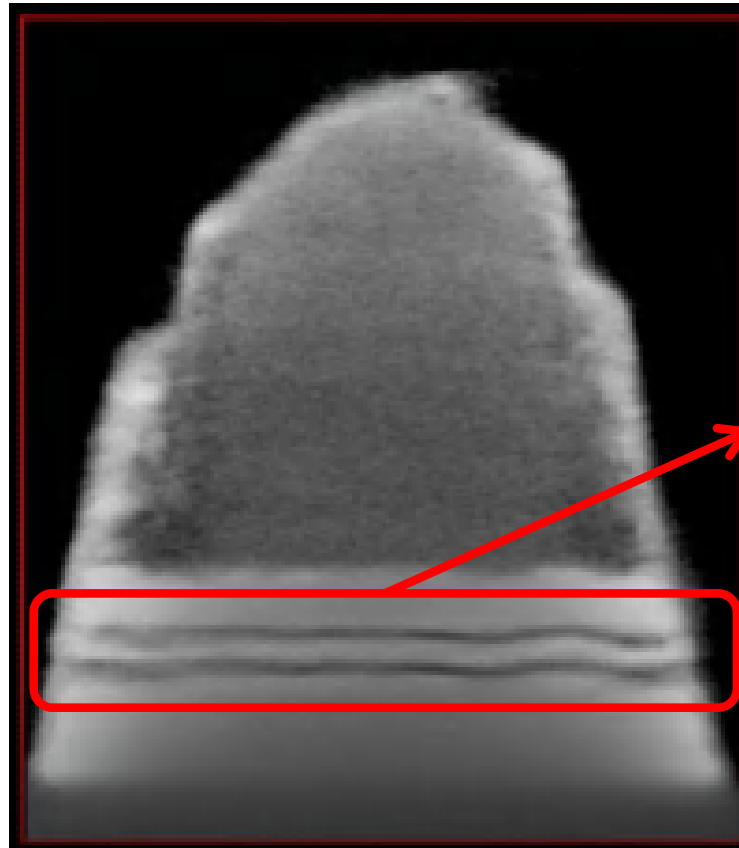
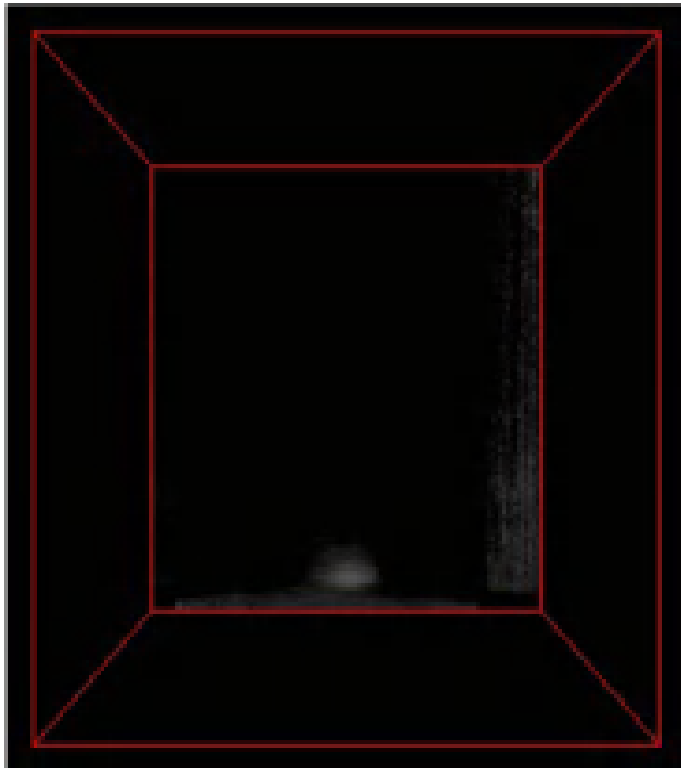
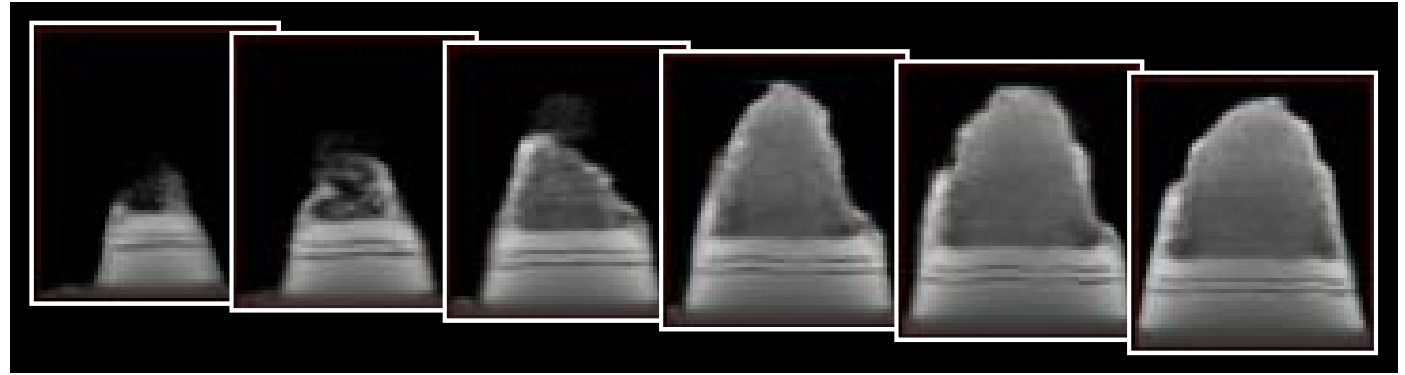
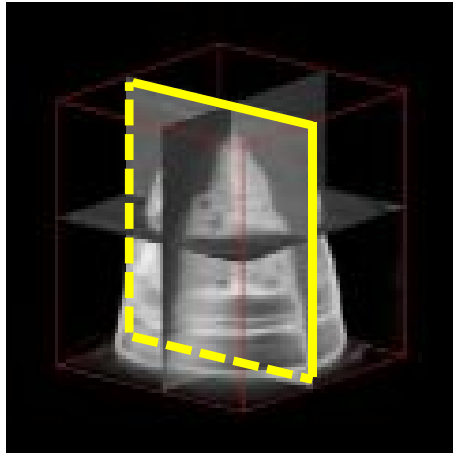
Top to bottom movie



Useful for process evaluation of hard mask

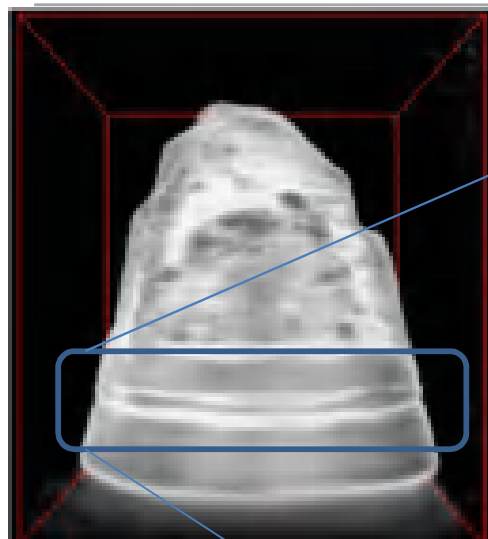


# Tomogram series : cross section

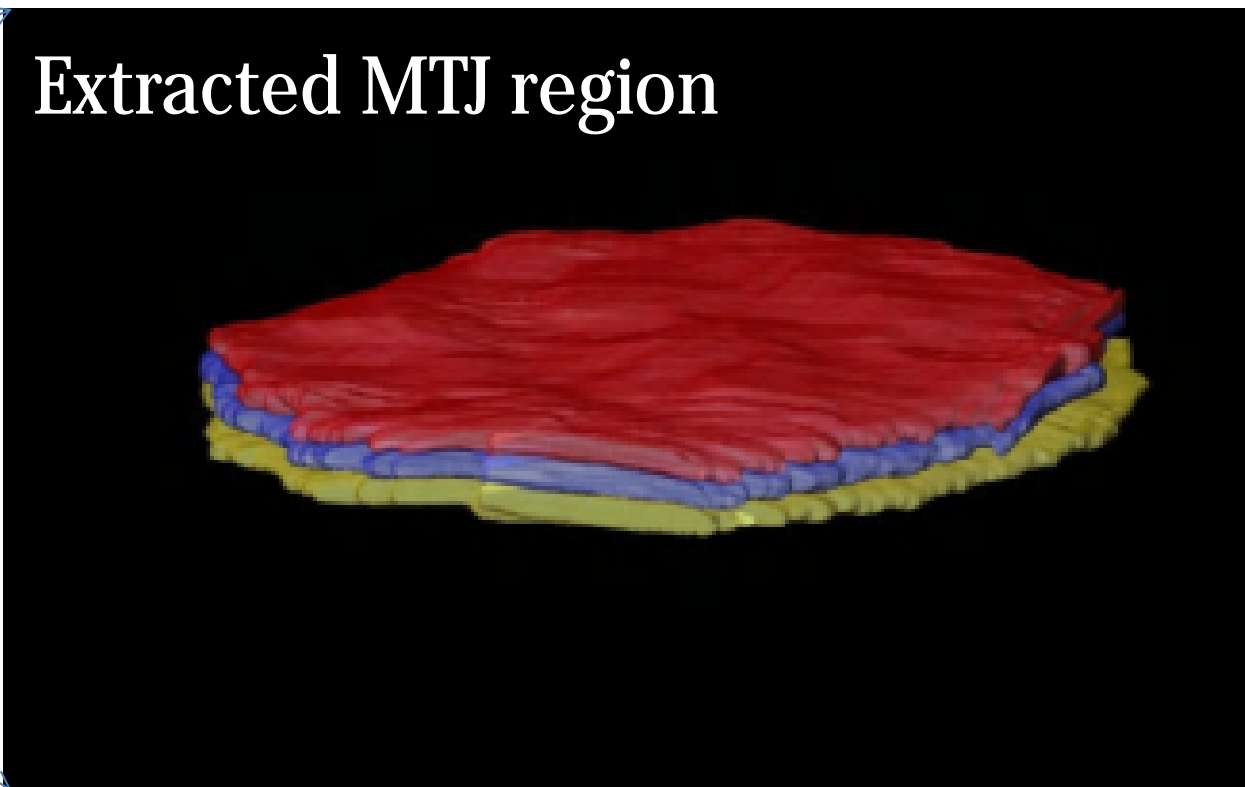


Evaluation of  
CFB/MgO roughness and  
thickness  
from “no-thickness”  
tomogram

# Quantitative analysis : segmentation



Extracted MTJ region

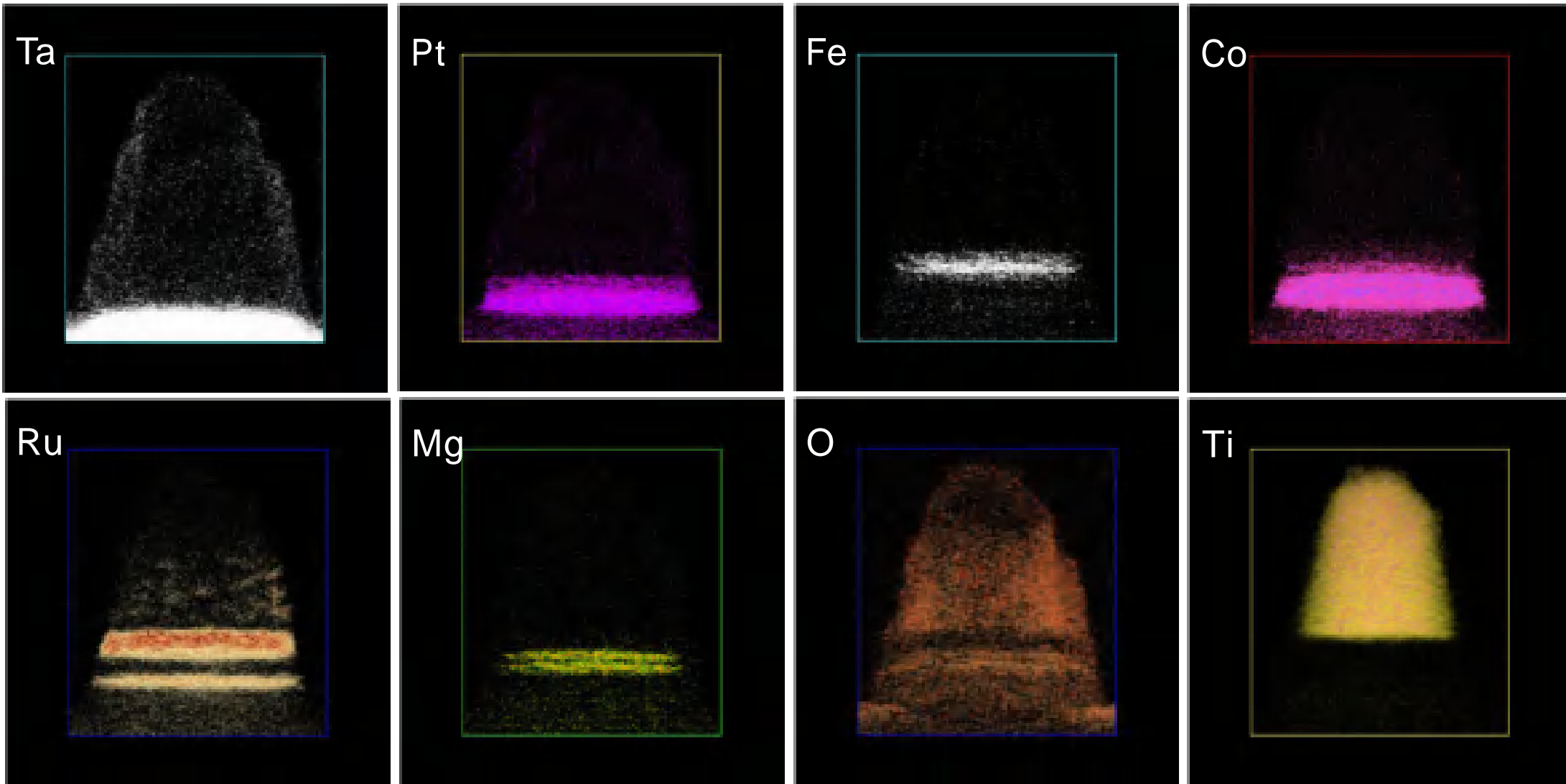


Extract “upper MgO / CFB / lower MgO” in 3D



The thickness / roughness information can be derived.

# STEM EDX tomography results 1



# STEM EDX tomography results 2

Ta+Pt+Ru+Mg+Fe

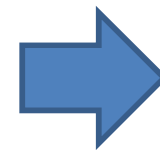


## Good points

- EDX tomogram revealed 1nm-order thin lamination structure.
- deposits consist of Ru.

## Bad points

- Roughness structure couldn't be recognized.
- Barrier edge detail structure couldn't be recognized.



Should be improved

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# Conclusion

- 80nm MTJ structure was investigated by 3D-TEM.
- “Rod-shape” FIB preparation made it possible to get higher resolution ( $<1\text{nm}$ ) 3D tomogram.

*HAADF-STEM tomogram revealed the thickness or roughness of barrier MgOs quantitatively, and this technique will be popular to evaluate MRAM process.*

*EDX tomography gave us the information about deposits or damaged layer distribution roughly.*

## Future subject

- Barrier edge structure analysis more precisely.
- 3D-EELS (higher resolution and chemical information)
- More information about spin or crystal structure